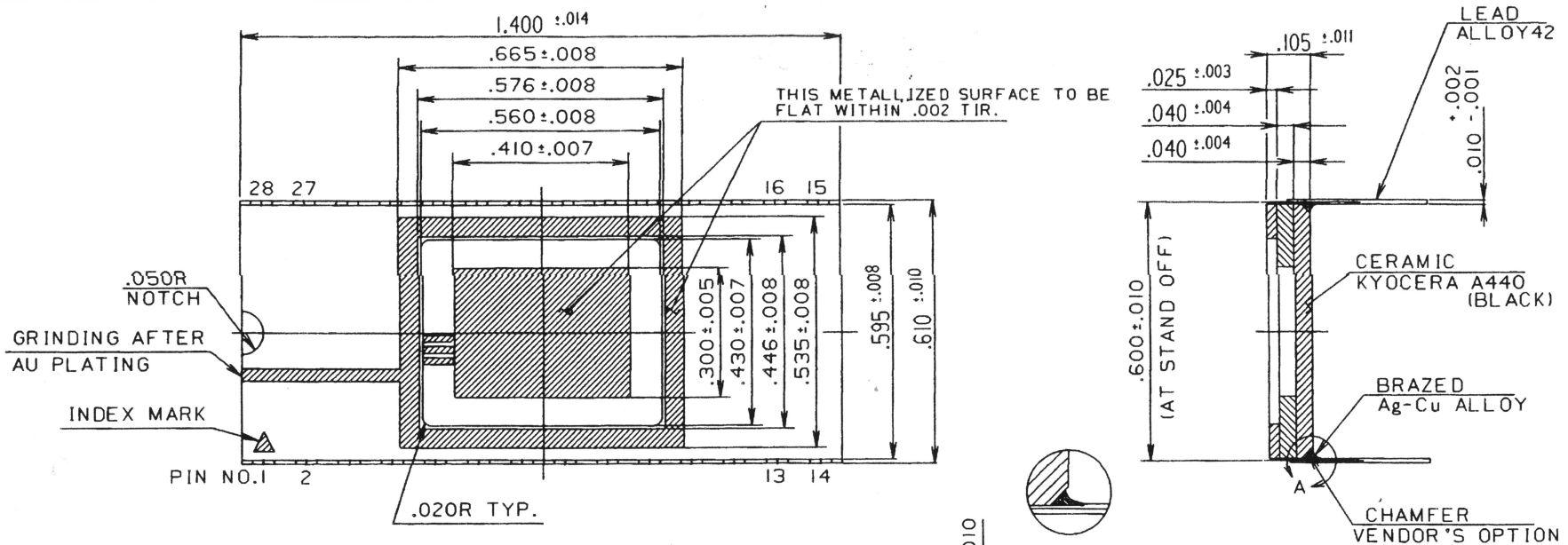


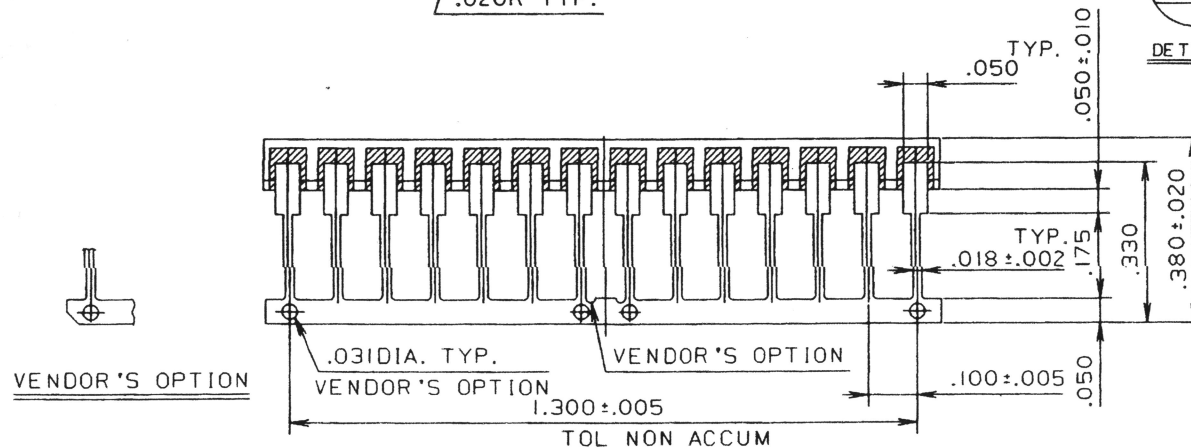
SSM P/N CSB02839



DETAIL - A

NOTES

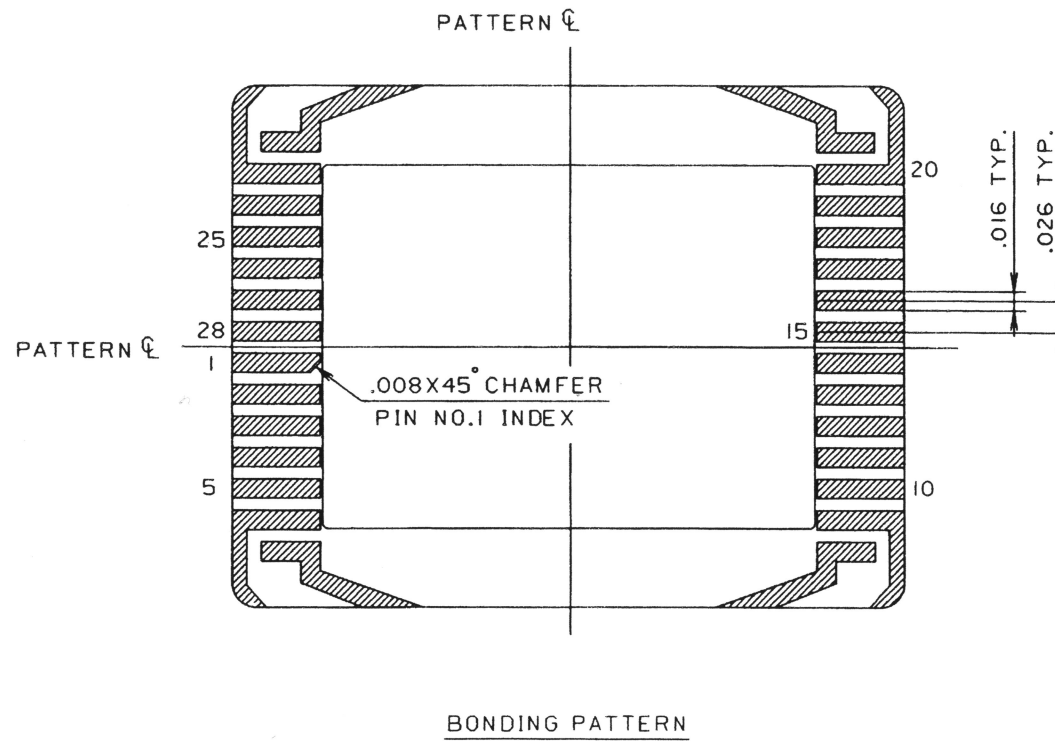
1. PLATING THICKNESS TO BE PER CUSTOMER'S SPECIFICATION.
2. SEAL AREA TO BE METALLIZED.
3. DIE ATTACH AREA TO BE METALLIZED.
4. SEAL RING AND DIE ATTACH PAD TO BE FLOATING FROM ANY PINS.
5. LEAD RESISTANCE : 0.30 Ω MAX.



SB028Z464-1 S=8

MODIFICATION						NAME	TOLERANCE	DRAWN	CHECKED	APPROVED	DATE
						28 LEAD SIDE BRAZED PACKAGE	UNLESS OTHERWISE SPECIFIED	S.F	K.K	T.A	M.K
						SCALE 4/1	±.005				JUN.11.91
						MATERIAL AS INDICATED	THIRD ANGLE PROJECTION				
						KYOCERA	KYOCERA CORPORATION KYOTO JAPAN	DRAWING NO.			SHEET
CHANGED					DATE	DRAWN	CHECKED	APPROVED	KD-S91464		1/2





MODIFICATION						NAME	TOLERANCE	DRAWN	CHECKED	APPROVED	DATE
						28 LEAD SIDE BRAZED PACKAGE	UNLESS OTHERWISE SPECIFIED	S.F	K.K	T.A	M.K
						SCALE 10/1	MATERIAL				
							THIRD ANGLE PROJECTION	<i>S. Fuka</i>	<i>K. Kama</i>	<i>T. Arai</i>	<i>M. Iwata</i>
								DRAWING NO.			SHEET
CHANGED		DATE	DRAWN	CHECKED	APPROVED	KYOCERA CORPORATION KYOTO JAPAN		KD-S91464			2/2